PRESIDIO COMPONENTS RF POWER STACKSTM

PRESIDIO ADVANTAGE

Ultra Lowest ESL

Typically less than half, as a result of the vertical plate design.

Ultra Low ESR

Due to internal vertical plate design, high Q porcelain ceramic and capacitor electrode connection directly to the printed circuit board.

Integrated Heat Sink

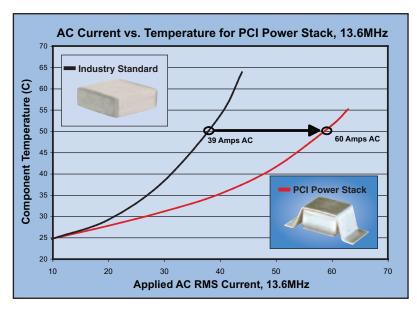
Best heat dissipation is achieved by integrating 'heat sink' electrodes with direct connection to the base plate.

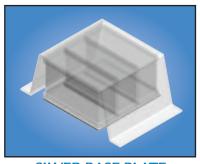
Best Vibration Performance

Robust base plate and dual top lead attachment provide superior vibration tolerance.

TYPICAL APPLICATIONS

- High RF Power for Commercial, Military and Space
- Non-Magnetic and Antenna Applications
- Semiconductor Manufacturing Equipment





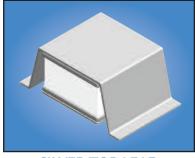
SILVER BASE PLATE



VERTICAL STACKED
CAPACITORS



INTEGRATED "HEAT SINK" ELECTRODES



SILVER TOP LEAD

Consult Presidio for additional information and samples.

PATENT PENDING

